

Abstract

- 5 Organopolysiloxane compositions that cure by the addition reaction of
silicon-bonded lower alkenyl radicals with silicon-bonded hydrogen atoms
and which exhibit select adhesion to a variety of substrates. The
compositions comprise an adhesion promoting mixture comprising an
epoxy-functional compound, soluble polydiorganosiloxanes,
10 polycycloorganosiloxanes (linear and cyclic) and and hydroxy end blocked
hydrocarbons (glycols) thus giving release characteristics to metal
substrates while maintaining adhesion to a thermoplastic substrate.
10 Additionally, an additive may be used to produce surface lubricity after
curing.

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